

- 1. MODEL** TS6132U(D)
Single track, three zone hotplate, single or double cassette
- 2. PHYSICAL** DIMENSIONS:
1525mm (W)x 910mm (D)x 900mm (H) ... TS6131U(D) 60in. x 35.5in. x 36in.
- 3. WAFER SIZE** 150mm Max. (4 or 5-6 inch capability)

4. MAJOR COMPONENTS

4.1. SEND & RECEIVE UNIT:

Each unit accommodates one or two cassettes, Fluoroware type with pitch of 3/16" (for 25 Wafers)

4.2. COAT UNIT:

- 1. Single or Double set with SOG1 nozzles of 0.85mm I.D. (1/16 in. tubing)
Nozzle rinse1 nozzle of 0.85mm I.D.
- 2. No-dry nozzle Nozzle Capping mechanism (PATENTED)
Nozzle Cleaning with solvent (PAT. PENDING)
- 3. Catch cup Extra wide design to prevent splashback
Cup cleaning with solvent
- 4. Non-drip nozzles Equipped with adjustable suckback valve
- 5. Waste recovery 1 gal. (Polypropylene tank) or optional s.s. can
- 6. Catch cup PVC 278 mm I.D. (11") (PE optional)
- 7. Solvent tubing Teflon
- 8. Suckback valve Teflon
- 9. Fluid containers SOG one 125/250cc or one 500cc or both
IPA one 3 gallon stainless steel code-2 canister
two canisters optional (one for nozzle rinse and back side
rinse, one for cup rinse)

4.3. BAKE UNIT:

- 1. Three vacuum chuck hot plates Baking temperature range per plate, individually
programmable: room temp. -- 250°C or 350°C.
- 2. Heater Capacity 3.8 kw. (total) @ 250°C (5.0kw @ 350°C option)
- 3. Baking Time 0-999.9 secs with increments of 0.1 sec
- 4. Normal indicator setting $\pm 3^{\circ}\text{C}$